# Power MOSFET 30V, $89m\Omega$ , 3A, Single N-Channel

This low-profile high-power MOSFET is produced using ON Semiconductor's trench technology, which is specifically designed to minimize gate charge and ultra low on resistance. This device is suitable for applications with low gate charge driving or ultra low on resistance requirements.

#### **Features**

- Low On-Resistance
- 1.8V drive
- ESD Diode-Protected Gate
- Pb-Free, Halogen Free and RoHS compliance
- Ultra small package SCH6 (1.6mm×1.6mm×0.56mmt)

## **Typical Applications**

• Load Switch

#### **SPECIFICATIONS**

#### **ABSOLUTE MAXIMUM RATING** at Ta = 25°C (Note 1)

Parameter	Symbol	Value	Unit
Drain to Source Voltage	VDSS	30	V
Gate to Source Voltage	VGSS	±12	٧
Drain Current (DC)	ID	3	Α
Drain Current (Pulse) PW ≤ 10µs, duty cycle ≤ 1%	IDP	12	Α
Power Dissipation When mounted on ceramic substrate (900mm²×0.8mm)	PD	0.8	W
Junction Temperature	Tj	150	°C
Storage Temperature	Tstg	-55 to +150	°C

Note 1: Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL RESISTANCE RATINGS

THE RUMAE REGIOTARGE RATINGS					
Parameter	Symbol	Value	Unit		
Junction to Ambient When mounted on ceramic substrate (900mm² × 0.8mm)	$R_{\theta JA}$	156.2	°C/W		

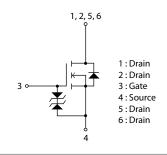


### ON Semiconductor®

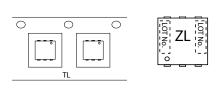
www.onsemi.com

VDSS	R <sub>DS</sub> (on) Max	ID Max
	89mΩ@ 4.5V	
30V	126mΩ@ 2.5V	3A
	195mΩ@ 1.8V	

# ELECTRICAL CONNECTION N-Channel



#### PACKING TYPE: TL MARKING



#### ORDERING INFORMATION

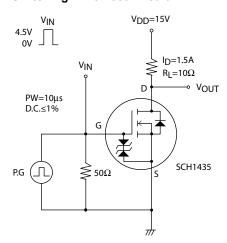
See detailed ordering and shipping information on page 5 of this data sheet.

**ELECTRICAL CHARACTERISTICS** at Ta = 25°C (Note 2)

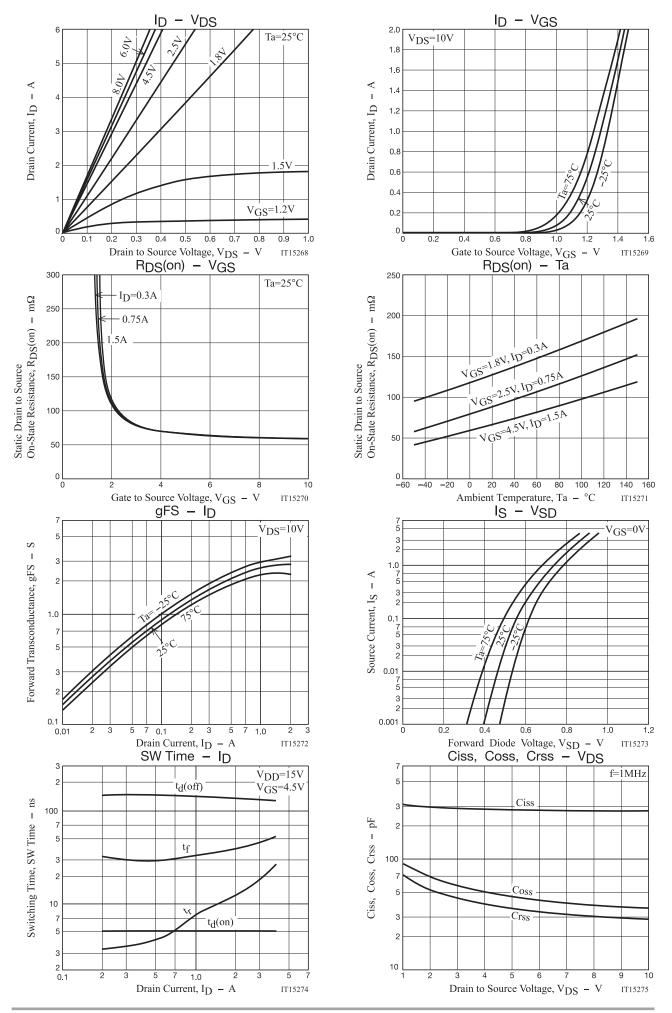
Parameter	Current ed			Value		
Parameter	Symbol	Conditions	min	typ	max	Unit
Drain to Source Breakdown Voltage	V(BR)DSS	ID=1mA, VGS=0V	30			V
Zero-Gate Voltage Drain Current	IDSS	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V			1	μА
Gate to Source Leakage Current	IGSS	V <sub>GS</sub> =±8V, V <sub>DS</sub> =0V			±10	μА
Gate Threshold Voltage	VGS(th)	V <sub>DS</sub> =10V, I <sub>D</sub> =1mA	0.4		1.3	V
Forward Transconductance	gFS .	V <sub>DS</sub> =10V, I <sub>D</sub> =1.5A		2.7		S
Static Drain to Source On-State Resistance	R <sub>DS</sub> (on)1	I <sub>D</sub> =1.5A, V <sub>GS</sub> =4.5V		68	89	mΩ
	R <sub>DS</sub> (on)2	I <sub>D</sub> =0.75A, V <sub>GS</sub> =2.5V		90	126	mΩ
	RDS(on)3	I <sub>D</sub> =0.3A, V <sub>G</sub> S=1.8V		130	195	mΩ
Input Capacitance	Ciss			265		pF
Output Capacitance	Coss	V <sub>DS</sub> =10V, f=1MHz		35		pF
Reverse Transfer Capacitance	Crss			28		pF
Turn-ON Delay Time	t <sub>d</sub> (on)			5.1		ns
Rise Time	t <sub>r</sub>	Occupation of Table Office 14		10		ns
Turn-OFF Delay Time	t <sub>d</sub> (off)	See specified Test Circuit		137		ns
Fall Time	tf			36		ns
Total Gate Charge	Qg			3.5		nC
Gate to Source Charge	Qgs	V <sub>DS</sub> =15V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =3A		0.57		nC
Gate to Drain "Miller" Charge	Qgd			0.93		nC
Forward Diode Voltage	V <sub>SD</sub>	IS=3A, VGS=0V		0.87	1.2	V

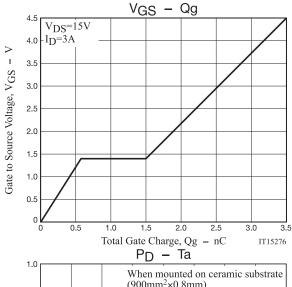
Note 2 : Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

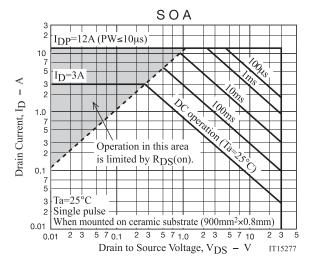
# **Switching Time Test Circuit**

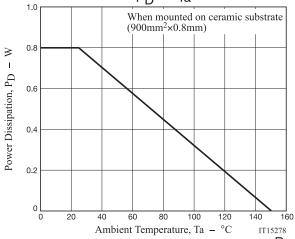


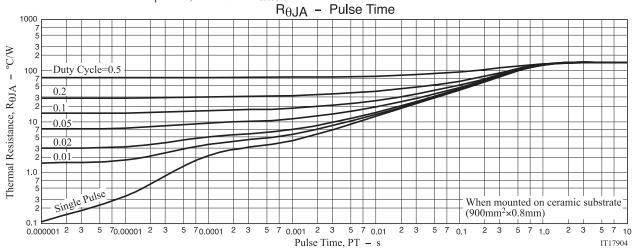
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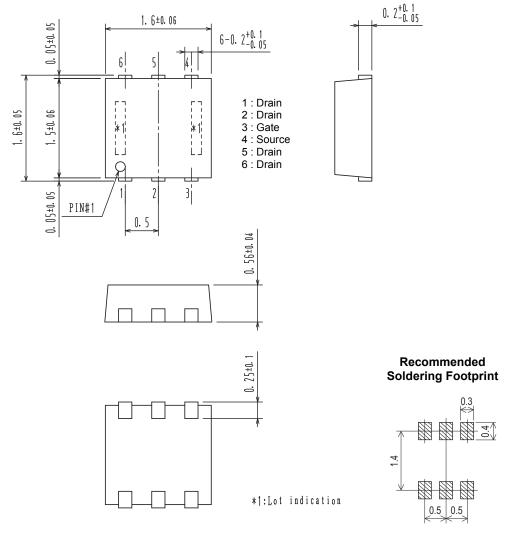






#### PACKAGE DIMENSIONS

unit: mm SOT-563 / SCH6 CASE 463AB ISSUE O



#### **ORDERING INFORMATION**

Device	Marking	Package	Shipping (Qty / Packing)	
SCH1435-TL-H	71	SOT-563 / SCH6	5,000 / Tape & Reel	
SCH1435-TL-W	ZL	(Pb-Free / Halogen Free)		

<sup>†</sup> For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. http://www.onsemi.com/pub\_link/Collateral/BRD8011-D.PDF

Note on usage: Since the SCH1435 is a MOSFET product, please avoid using this device in the vicinity of highly charged objects.

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